



Material Content Data Sheet



Sales Product Name	TLE6230GP			Issued	28. August 2013			
MA#	MA000710008							
Package	PG-DSO-36-48			Weight*	2043.97 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.906	0.58	0.58	5825	5825
leadframe	inorganic material	phosphorus	7723-14-0	0.383	0.02		187	
	non noble metal	zinc	7440-66-6	1.533	0.08		750	
	non noble metal	iron	7439-89-6	30.652	1.50		14996	
wire	non noble metal	copper	7440-50-8	1244.598	60.89	62.49	608912	624845
	non noble metal	copper	7440-50-8	2.422	0.12	0.12	1185	1185
	encapsulation	organic material	carbon black	1333-86-4	1.451	0.07		710
	plastics	epoxy resin	-	66.731	3.26		32648	
		inorganic material	silicondioxide	60676-86-0	657.160	32.15	35.48	321512
leadfinish	non noble metal	tin	7440-31-5	16.150	0.79	0.79	7901	7901
plating	noble metal	silver	7440-22-4	0.741	0.04	0.04	362	362
solder	noble metal	silver	7440-22-4	0.154	0.01		75	
	non noble metal	tin	7440-31-5	0.102	0.00		50	
	non noble metal	lead	7439-92-1	9.988	0.49	0.50	4887	5012
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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